

Fig. 1. Influence of additives (a–c) and base parameters (d, i) at bond strength R_p in different types of curing conditions

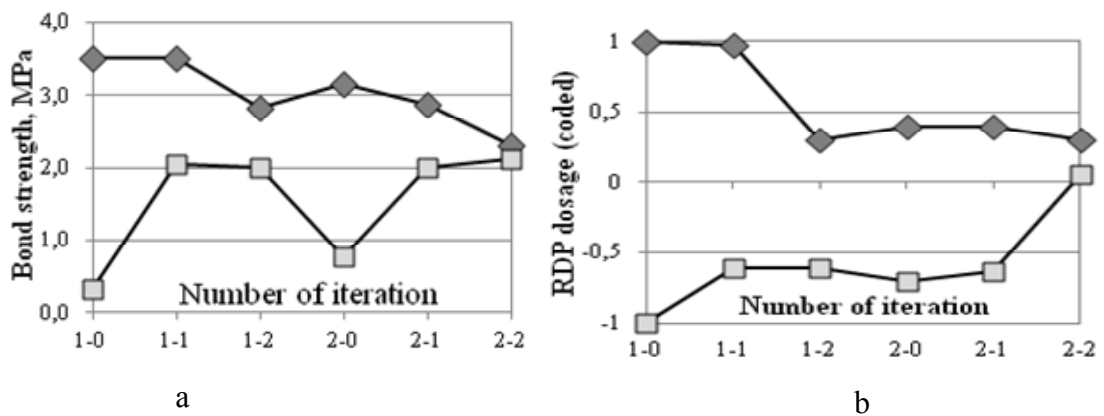


Fig. 2. Transforming of corridor of possible bond strength values (a) and dosage of RDP additive (b) at the iteration process